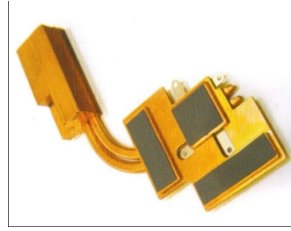


NON-SILICONE THERMAL FILLER PAD

3.0W/m.K, 70 SHORE 00, 400x200x0.5~3.0Tmm

W3TF300H

The W3TF300H non-silicone thermal filler pad is an EPDM polymer-based material that eliminates the risk of silicone oil leakage on electronic boards. The thermal conductive pad is able to overcome virtually any adverse environment in addition to conducting heat away from electronic components.



PRODUCT APPLICATION

- Memory Modules, DVDs, Set-Top Box
- LED, Monitor, Touch Panel, Heat Sink
- Cell Phones, Wireless Products

Item	Unit	W3TF300H	Test Method
Thermal Conductivity	W/m.k	3.00	ASTM D5470
Hardness	Shore 00	70	ASTM D2240
Thickness	mm	0.5 ~ 2.0	ASTM D374
Density	g/cm ³	3.0	ASTM D792
Weight Loss	%	<1	120° / 24hrs
Elongation	%	250	ASTM D412
Insulation Strength	kV / mm	<3	ASTM D149
Max Temperature Range	°C	-40 ~ 125	-
Sheet Size	mm	400 x 200	-
Colour	-	Light Grey	Visual
Flammability Rating	UL	Equivalent to 94-V-0	-

AMEC Thermasol

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